

1A, 20V Schottky Barrier Surface Mount Rectifier

FEATURES

- Low forward voltage, high efficiency
- High speed switching
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- · Low stored charge
- For switching power supply
- Protection circuits

MECHANICAL DATA

- Case: SOD-323F
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 4.60mg (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	1	Α	
V_{RRM}	20	V	
I _{FSM}	5	Α	
T _{J MAX}	125	°C	
Package	SOD-323F		
Configuration	Single die		









SOD-323F



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNIT
Repetitive peak reverse voltage	V_{RRM}	20	V
Reverse voltage, total rms value	$V_{R(RMS)}$	14	V
Forward current	I _F	1	Α
Surge peak forward current 8.3ms single sine-wave superimposed on rated load	I _{FSM}	5	А
Junction temperature	T_J	-55 to +125	°C
Storage temperature	T _{STG}	-55 to +150	°C



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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-ambient thermal resistance	R _{eJA}	220	°C/W

Thermal Performance Note: Units mounted on PCB (10mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
	$I_F = 10 \text{mA}, T_J = 25 ^{\circ}\text{C}$		266	290	mV
Forward voltage ⁽¹⁾	$I_F = 100 \text{mA}, T_J = 25 ^{\circ}\text{C}$	V_{F}	337	360	mV
	$I_F = 1000 \text{mA}, T_J = 25^{\circ}\text{C}$		487	650	mV
	$V_R = 5V, T_J = 25^{\circ}C$		-	10	μA
Reverse current @ rated V _R ⁽²⁾	$V_R = 8V, T_J = 25^{\circ}C$	I_R	-	20	μA
	V _R = 15V, T _J = 25°C		-	50	μA
Junction capacitance	$f = 1MHz, V_R = 5V$	С	29	35	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
BAT201M3 RRG	SOD-323F	3,000 / 7" Tape & Reel	



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

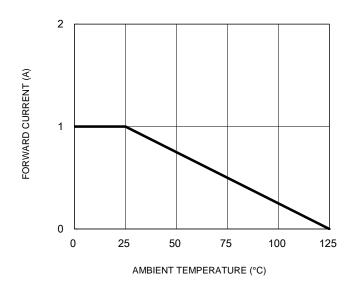


Fig.2 Typical Junction Capacitance

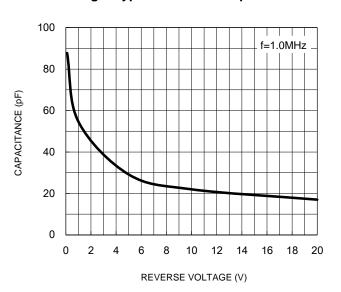


Fig.3 Typical Reverse Characteristics

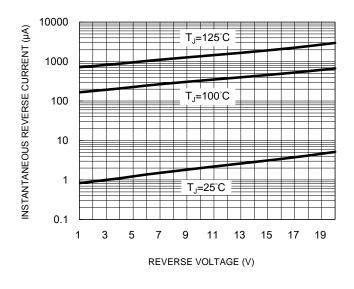
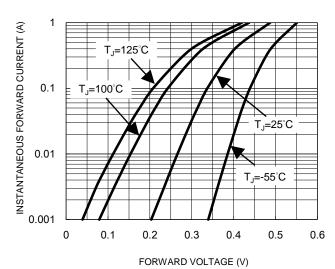


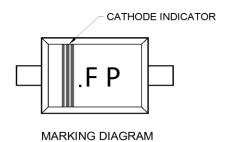
Fig.4 Typical Forward Characteristics





PACKAGE OUTLINE DIMENSIONS

SOD-323F ⊕ | 0.10 M | C | A | B | 2.50^{+0.30}_{-0.20} 0.40±0.10 0.325±0.075 ⊕ 0.10 M C A B 1.25±0.10 4 Α В 1.70±0.10 0.50±0.10 4 10° MAX 10° MAX **SEATING** $0.75^{+0.35}_{-0.15}$ **PLANE** $\begin{bmatrix} \mathbf{C} \end{bmatrix}$ 0.15^{+0.11} -0.10 2.00 -0.50 0.70



SUGGESTED PAD LAYOUT

- NOTES: UNLESS OTHERWISE SPECIFIED

 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PACKAGE OUTLINE REFERENCE: EIAJ ED-7500A-1, SC-90.
- MOLDED PLASTIC BODY LATERAL
 DIMENSIONS DO NOT INCLUDE MOLD
 FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DWG NO. REF: HQ2SD07-SOD323F-018 REV A.



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